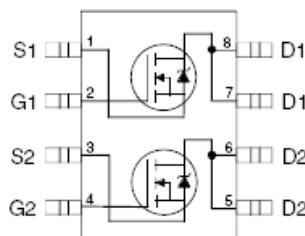


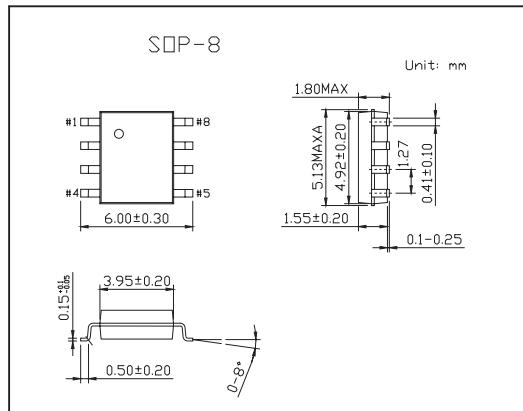
KRF7313

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Dual N-Channel Mosfet
- Surface Mount
- Fully Avalanche Rated



Top View



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain- Source Voltage	V _{DS}	30	V
Gate-to-Source Voltage	V _{Gs}	±20	
Continuous Drain Current, Ta = 25°C *3	I _D	6.5	A
Continuous Drain Current, Tc = 70°C *3	I _D	30	
Pulsed Drain Current	I _{DM}	2.5	
Maximum Power Dissipation Ta = 25°C*3	P _D	2	W
Maximum Power Dissipation Ta = 70°C *3		1.3	
Single Pulse Avalanche Energy *4	E _{AS}	82	mJ
Avalanche Current	I _{AR}	4	A
Repetitive Avalanche Energy	E _{AR}	0.2	mJ
Peak Diode Recovery dv/dt*2	dv/dt	5.8	V/ns
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150	°C
Maximum Junction-to-Ambient *3	R _{θ JA}	62.5	°C/W

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 I_{SD}≤4.0A, di/dt≤74A/μ s, V_{DD}≤V_{(BR)DSS}, T_J≤150°C

*3 Surface mounted on FR-4 board, t ≤ 10sec.

*4 Starting T_J=25°C ,L=10mH,R_G=25Ω , I_{AS}=4.0A

KRF7313

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250A	30			V
Breakdown Voltage Temp. Coefficient	△V _{(BR)DSS} /△T _J	I _D = 1mA, Reference to 25°C		0.022		V/°C
Static Drain-to-Source On-Resistance	R _{DSS(on)}	V _{GS} = 10V, I _D = 5.8A*1		0.023	0.029	Ω
		V _{GS} = 4.5V, I _D = 4.7A*1		0.032	0.046	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.0			V
Forward Transconductance	g _{fS}	V _{DS} = 15V, I _D = 5.8A*1		14		S
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1.0	μA
		V _{DS} = 24V, V _{GS} = 0V, T _J = 55°C			25	
Gate-to-Source Forward Leakage	I _{GSS}	V _{GS} = 20V			100	nA
Gate-to-Source Reverse Leakage		V _{GS} = -20V			-100	
Total Gate Charge	Q _g	I _D = 5.8A		22	33	nC
Gate-to-Source Charge	Q _{gs}	V _{DS} = 15V		2.6	3.9	
Gate-to-Drain ("Miller") Charge	Q _{gd}	V _{GS} = 10V,*1		6.4	9.6	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15V		8.1	12	ns
Rise Time	t _r	I _D = 1.0A		8.9	13	
Turn-Off Delay Time	t _{d(off)}	R _G = 6.0 Ω		26	39	
Fall Time	t _f	R _D = 15 Ω *1		17	26	
Input Capacitance	C _{iss}	V _{GS} = 0V		650		pF
Output Capacitance	C _{oss}	V _{DS} = 25V		320		
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		130		
Continuous Source Current (Body Diode)	I _s	MOSFET symbol showing the integral reverse p-n junction diode.			2.5	A
Pulsed Source Current (Body Diode) *2	I _{SM}				30	
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _s = 1.7A, V _{GS} = 0V*1		0.78	1.0	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 1.7A		45	68	ns
Reverse RecoveryCharge	Q _{rr}	di/dt = 100A/ μs*1		58	87	μC

*1 Pulse width ≤ 300 μs; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max